

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chien-Hsing Lee</td> <td>09/03/2008</td> </tr> <tr> <td>Tsung-Min Hsieh</td> <td>09/03/2008</td> </tr> <tr> <td>Chih-Hsiang Lin</td> <td>09/03/2008</td> </tr> </tbody> </table>		Name	Execution Date	Chien-Hsing Lee	09/03/2008	Tsung-Min Hsieh	09/03/2008	Chih-Hsiang Lin	09/03/2008
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Chien-Hsing Lee	09/03/2008								
Tsung-Min Hsieh	09/03/2008								
Chih-Hsiang Lin	09/03/2008								
RECEIVING PARTY DATA									
Name:	Solid State System Co., Ltd.								
Street Address:	5F-1, No. 22, Taiyuen Street, Jubei City,								
City:	Hsinchu								
State/Country:	TAIWAN								
Postal Code:	302								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12203151</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12203151				
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Application Number:	12203151								
CORRESPONDENCE DATA									
Fax Number:	(949)660-0809								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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Email:	usa@jcipgroup.com.tw								
Correspondent Name:	JIANQ CHYUN INTELLECTUAL PROPERTY								
Address Line 1:	7F-1,NO.100,ROOSEVELT RD.,SEC.2,								
Address Line 4:	Taipei, TAIWAN 100								
ATTORNEY DOCKET NUMBER:	28450-US-PA								
NAME OF SUBMITTER:	Belinda Lee								
Total Attachments: 2 source=28450assignment#page1.tif source=28450assignment#page2.tif									

CH \$40.00 12203151

PATENT

ASSIGNMENT

WHEREAS,

1. Chien-Hsing Lee
2. Tsung-Min Hsieh
3. Chih-Hsiang Lin

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **MICRO-ELECTRO-MECHANICAL SYSTEMS (MEMS) PACKAGE AND METHOD FOR FORMING THE MEMS PACKAGE**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Solid State System Co., Ltd.
of 5F-1, No. 22, Taiyuen Street, Jubei City, Hsinchu, Taiwan 302, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Chien-Hsing Lee
Sole or First Joint Inventor: Chien-Hsing Lee

Date: 2008/9/3

Signature: Tsung-Min Hsieh
Second Joint Inventor (if any): Tsung-Min Hsieh

Date: 2008/9/3

Signature: Chih-Hsiang Lin
Third Joint Inventor (if any): Chih-Hsiang Lin

Date: 2008/9/3